



THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Bailey et al.

Serial No.: 09/452,691

Filed: 12/02/99

For: AN INTEGRATED CIRCUIT HAVING A THIN FILM RESISTOR
LOCATED WITHIN A MULTILEVEL DIELECTRIC BETWEEN AN
UPPER AND LOWER METAL INTERCONNECT LAYER

Docket No.: TI-27935

Examiner: Fenty, J.

Art Unit: 2815

Amendment under 37 CFR 1.115

Assistant Commissioner of Patents
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that this correspondence is being deposited with
the U.S. Postal Service as First Class Mail in an envelope addressed
to: Assistant Commissioner for Patents, Washington, D.C. 20231 on

11-1-01

Marianna Smith
Marianna Smith

Dear Sir:

The following amendments and remarks are offered in response to the
Examiner's Office Action dated 06/01/01. They are respectfully submitted as a
full and complete response to that Action.

Please amend the above-referenced application as follows:

In the Title:

Replace the Title of the Invention with the following:

—AN INTEGRATED CIRCUIT HAVING A THIN FILM RESISTOR LOCATED
WITHIN A MULTILEVEL DIELECTRIC BETWEEN AN UPPER AND LOWER
METAL INTERCONNECT LAYER—